# **Single Buffer**

The NL17SH34 MiniGate  $^{\text{\tiny M}}$  is an advanced high-speed CMOS Buffer in ultra-small footprint.

The NL17SH34 input structure provides protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

#### **Features**

- High Speed:  $t_{PD} = 3.5 \text{ ns}$  (Typ) at  $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1.0 \mu A$  (Max) at  $T_A = 25$ °C
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Package
- These are Pb-Free and Halide-Free Devices

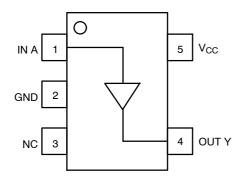


Figure 1. Pinout (Top View)

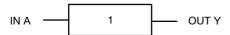


Figure 2. Logic Symbol



# ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



SOT-953 CASE 527AE



2 = Specific Device Code (Rotated 90°)

M = Month Code

PIN ASSIGNMENT					
1	IN A				
2	GND				
3	NC				
4	OUT Y				
5	V <sub>CC</sub>				

## **FUNCTION TABLE**

A Input	Y Output
L	L
Н	Н

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage $V_{IN} = 0$ High or Low State	-0.5 to +7.0 -0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current $V_{OUT} < GND, V_{OUT} > V_{CC}$	±20	mA
l <sub>OUT</sub>	DC Output Source/Sink Current	±25	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	50	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage  Human Body Model (Note 2)  Machine Model (Note 3)  Charged Device Model (Note 4)	>2000 >200 N/A	V
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Characteristics			Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage		0.0	5.5	V
V <sub>OUT</sub>	Output Voltage	0.0	$V_{CC}$	V	
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
Δt / ΔV	Input Transition Rise or Fail Rate $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 5.0 \text{ V}$	± 0.3 V ± 0.5 V	0 0	100 20	ns/V

### DC ELECTRICAL CHARACTERISTICS

			Vcc	V <sub>CC</sub> T <sub>A</sub> = 25°C			$T_A \leq 85^{\circ}C$		-55°C to 125°C		
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 2.0	0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>				٧
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>				
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 2.0			0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	٧
			2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OH</sub>	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50  \mu\text{A}$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OH} = -4$ mA $I_{OH} = -8$ mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V <sub>OL</sub>	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50  \mu\text{A}$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OL} = 4$ mA $I_{OL} = 8$ mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			1.0		10		40	μΑ

# AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$ )

		V <sub>CC</sub>	Test	T <sub>A</sub> = 25°C		$T_A \leq 85^{\circ}C$		−55°C to 125°C			
Symbol	Parameter	(V)	Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay, A to Y	3.0 to 3.6	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF		4.5 6.4	7.1 10.6		8.5 12.0		10.0 14.5	ns
		4.5 to 5.5	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF		3.5 4.5	5.5 7.5		6.5 8.5		8.0 10.0	
C <sub>IN</sub>	Input Capacitance				4.0	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	5.0			8.0						pF

<sup>6.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

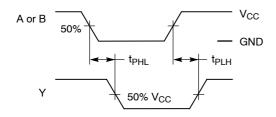
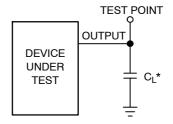


Figure 3. Switching Waveforms



\*Includes all probe and jig capacitance.

Figure 4. Test Circuit

# **ORDERING INFORMATION**

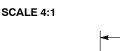
Device	Package	Shipping <sup>†</sup>
NL17SH34P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel

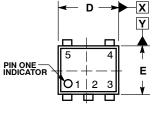
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



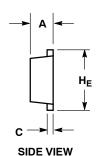
CASE 527AE **ISSUE E** 

**DATE 02 AUG 2011** 

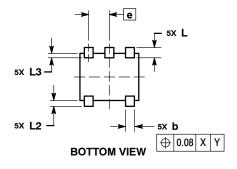




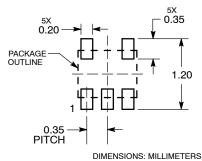
**TOP VIEW** 



SOT-953



#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS
  MAXIMUM LEAD THICKNESS INCLUDES LEAD
  FINISH, MINIMUM LEAD THICKNESS IS THE
  MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD
  FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS						
DIM	MIN NOM MAX						
Α	0.34	0.37	0.40				
b	0.10	0.15 0.20					
С	0.07	0.07 0.12 0.13					
D	0.95	1.00	1.05				
E	0.75	0.80	0.85				
е		0.35 BS	С				
HE	0.95	95 1.00 1.05					
L	0.175 REF						
L2	0.05	0.10	0.15				
L3			0.15				

### **GENERIC MARKING DIAGRAM\***



= Specific Device Code = Month Code

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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